

APPARATUS FOR MOLDING A SEMICONDUCTOR WAFER AND PROCESS
THEREFOR

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ABSTRACT

Mold pieces (105 and 110) for molding a layer of mold compound on the interconnect side of a bumped semiconductor wafer (118) include a primary cavity (117) and secondary cavities (120) into which excess mold compound from the primary cavity
10 (117) flows. The secondary cavities (120) include a plunger (130) that asserts a predetermined backpressure that is equal to a desired mold compound pressure on the mold compound during molding. In this way, most of the excess mold compound is forced into the secondary cavities (120) and the mold compound is under the desired mold compound pressure. As most of the excess mold compound in the primary cavity (117)
15 flows into the secondary cavities (120), this advantageously leaves a relatively thin layer of mold compound on the semiconductor wafer (118). This thin layer of mold compound is then advantageously removed, for example by grinding, in a relatively short time.

FIG. 1 accompanies this abstract.
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